

#2 | PreAmend A
7-16-01
R. H. H.

PATENT
Attorney Docket No. 401171/FUKAMI

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

AGA et al.

Art Unit: Unknown

Application No.: Unknown

Examiner: Unknown

Filed: April 20, 2001

For: EPOXY RESIN
COMPOSITION,
SEMICONDUCTOR
DEVICE, AND METHOD
OF JUDGING
VISIBILITY OF LASER
MARK

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to the examination of the above-identified patent application, please enter the following amendments and consider the following remarks.

IN THE SPECIFICATION:

Replace the paragraph beginning at page 1, line 6 with:

The present invention generally relates to an epoxy resin composition for sealing a semiconductor device, and more specifically to a semiconductor sealing epoxy resin composition providing excellent visibility of a laser mark and having excellent fluidity characteristics. The present invention also relates to a semiconductor device that uses such a semiconductor sealing epoxy resin composition. The present invention further relates to a method of judging the visibility of a laser mark.